

# **HVU202A**

# Variable Capacitance Diode for Electronic Tuning

REJ03G0104-0500Z

(Previous: ADE-208-034D)

Rev.5.00 Sep.29.2003

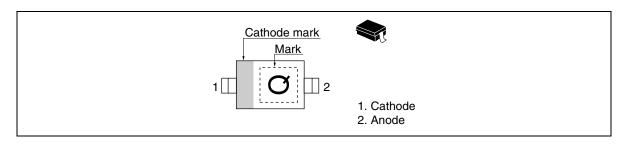
#### **Features**

- Low series resistance and good C-V linearity.
- Suitable for compact ET tuner.
- Ultra small Resin Package (URP) is suitable for surface mount design.

## **Ordering Information**

Type No.	Laser Mark	Package Code
HVU202A	Q	URP

#### **Pin Arrangement**



### **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit
Reverse voltage	V <sub>R</sub>	34	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

#### **Electrical Characteristics**

 $(Ta = 25^{\circ}C)$ 

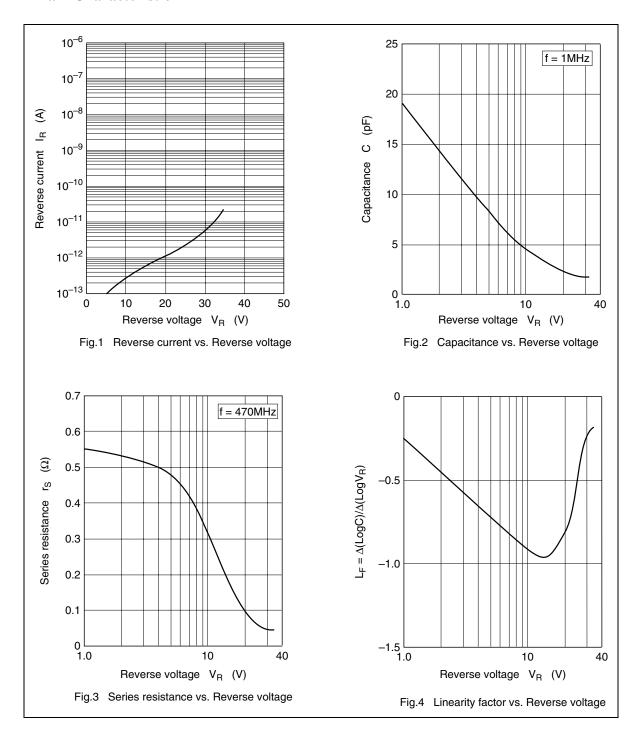
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I <sub>R1</sub>	_	_	10	nA	V <sub>R</sub> = 32 V
	I <sub>R2</sub>	_	_	100	_	V <sub>R</sub> = 32 V, Ta = 60°C
Capacitance	C <sub>2</sub>	14.11	_	16.47	рF	V <sub>R</sub> = 2 V, f = 1 MHz
	C <sub>25</sub>	2.06	_	2.35	_	V <sub>R</sub> = 25 V, f = 1 MHz
Capacitance ratio	n	6.20	_	_	_	C <sub>2</sub> /C <sub>25</sub>
Series resistance	r <sub>s</sub>	_	_	0.57	Ω	V <sub>R</sub> = 5 V, f = 470 MHz
Matching error	∆C/C *1	_	_	2.00	%	V <sub>R</sub> = 2 to 25 V, f = 1 MHz

Note: 1. C.C system (Continuous Connected taping system) enable to make any 10 pcs of ΔC/C continuous in a reel, expect extention to another group.

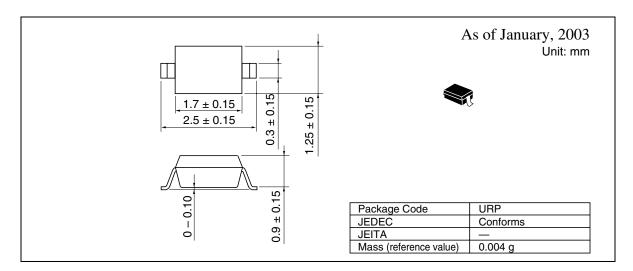
Calculate Matching Error,

$$\Delta C/C = \frac{(Cmax - Cmin)}{Cmin} \times 100 \text{ (\%)}$$

#### **Main Characteristic**



# **Package Dimensions**



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